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IN THE SPECIFICATION:

Please replace page 4, line 14 through page 5, line 10 of the specification with the following paragraphs:

A system level device for battery and integrated circuit chip integration comprising at least one battery; at least one integrated circuit chip powered by the at least one battery; and a package having a pair of opposed upright ends, the package connected to any of the at least one battery and the at least one integrated circuit chip, wherein the at least one integrated circuit chip may lay on top of a portion of the package, wherein the at least one battery may overhang the at least one integrated circuit chip, wherein the package may connect to the at least one integrated circuit chip through an interior portion of the package, wherein the at least one integrated circuit chip may connect to an upper indent portion of the package, wherein the at least one battery is preferably larger than the at least one integrated circuit chip, wherein the at least one battery preferably connects to an underside of the package, and wherein the at least one battery may further comprise a stack of connected batteries.

Another aspect of the invention provides a system level device for battery and integrated circuit chip integration comprising at least one battery; at least one integrated circuit chip powered by the at least one battery; and a package connected to any of the at least one battery and the at least one integrated circuit chip, wherein the at least one battery connects to a pair of opposed upright ends of the package, wherein the at least one integrated circuit chip is preferably disposed between the at least one battery and the package, and wherein the at least one integrated circuit chip preferably lays on top of a portion of the package.

Another embodiment of the invention provides a system level device for battery and

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integrated circuit chip integration comprising a multi-chip module integration system, wherein the multi-chip module integration system comprises a multi-chip module having a pair of opposed upright ends; at least one battery connected to the multi-chip module; and at least one integrated circuit chip connected to the battery, wherein the integrated circuit chip is powered by the battery, wherein the at least one battery preferably overhangs, and is larger than, the at least one integrated circuit chip, wherein the at least one integrated circuit chip lays on top of a portion of the multi-chip module, wherein the multi-chip module may connect to the at least one integrated circuit chip through an interior portion of the multi-chip module, and wherein the at least one integrated circuit chip may connect to an upper indent portion of the multi-chip module.

Another aspect of the invention provides a system level device for battery and integrated circuit chip integration comprising a multi-chip module integration system, wherein the multi-chip module integration system comprises a multi-chip module; at least one battery connected to the multi-chip module; and at least one integrated circuit chip connected to the battery, wherein the integrated circuit chip is powered by the battery, wherein the at least one battery preferably connects to a pair of opposed upright ends of the multi-chip module, wherein the at least one battery preferably overhangs; and is larger than, the at least one integrated circuit chip, and wherein the at least one integrated circuit chip may lay on top of a portion of the multi-chip module.

Another embodiment of the invention provides an integrated chip structure comprising an integrated circuit chip; a battery directly connected to the integrated circuit chip; and a package having a pair of opposed upright ends, the package connected to any of the battery and the integrated circuit chip, wherein the integrated circuit chip preferably lays on top of a portion of the package, and wherein the at least one battery preferably overhangs the at least one integrated

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circuit chip. Preferably, the integrated chip structure further comprises solder connections between the battery and the integrated circuit chip, wherein the solder connections may comprise an electrical connection between the battery and the integrated circuit chip, wherein the package preferably surrounds the battery and the integrated circuit chip, and wherein the battery is preferably directly connected to the package.

Another embodiment of the invention provides an integrated chip structure comprising a package having a pair of opposed upright ends; an integrated circuit chip mounted on the package; a battery directly connected to the package and electrically connected to the integrated circuit chip, wherein the integrated circuit chip preferably lays on top of a portion of the package, wherein the at least one battery may overhang the at least one integrated circuit chip, wherein the battery is preferably held adjacent to the integrated circuit chip by the package, wherein the package may be between the battery and the integrated circuit chip, wherein the battery is preferably electrically connected to the integrated circuit chip through the package, and wherein the battery may comprise multiple batteries stacked on the package.